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Lecture 3: Intro to CMOS Process II

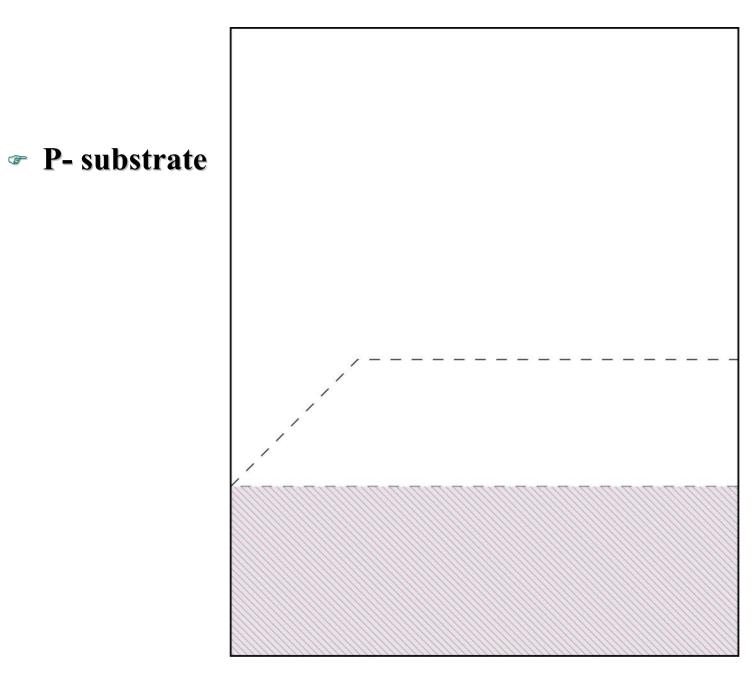
Generic Process Flow for a CMOS Inverter

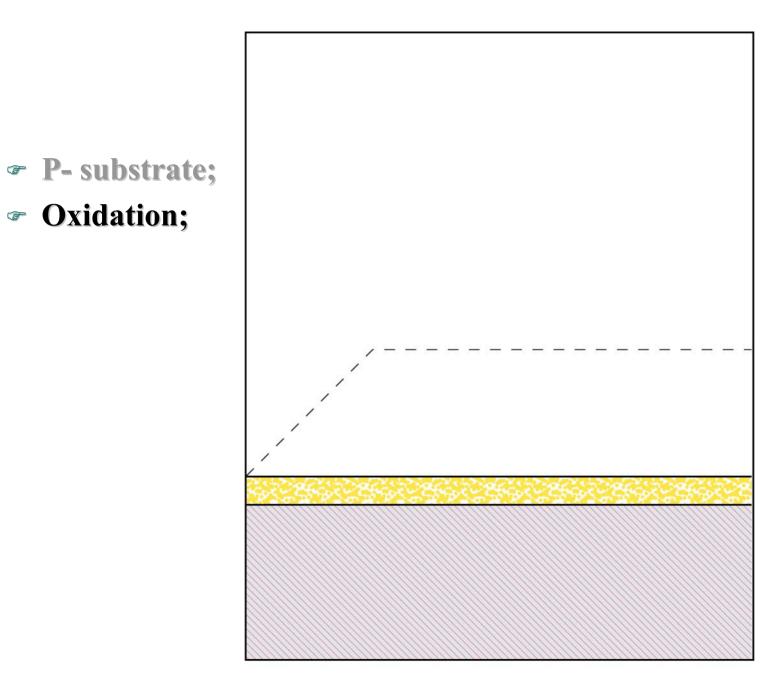
Readings: Chapter 2

Lecture 3 - Outline

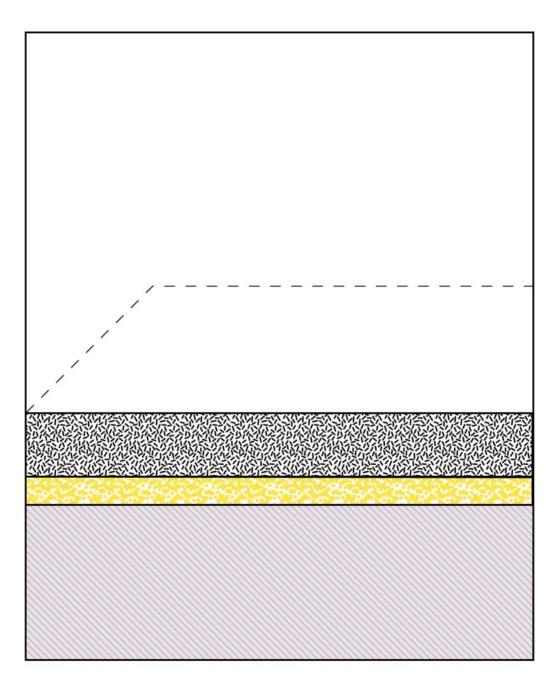
Generic Complimentary Metal-Oxide-Semiconductor (CMOS) Process:

- Processing steps
- N-well process flow
- Lithographic masks
- 3-D structures





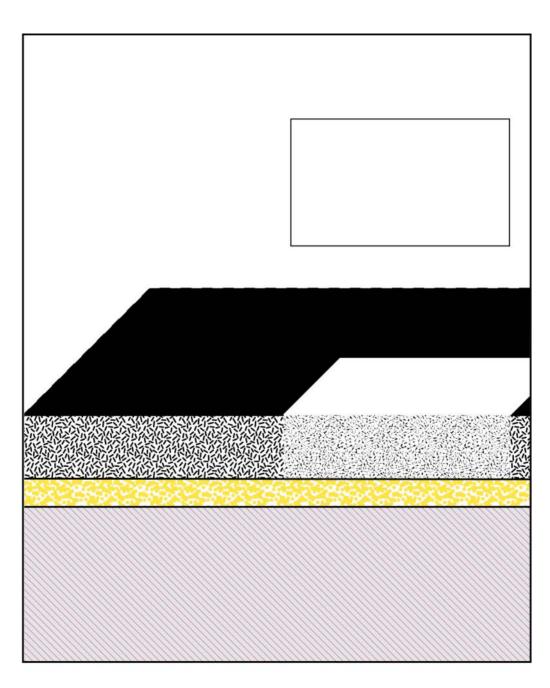
- P- substrate;
- Oxidation;
- Photoresist deposition;



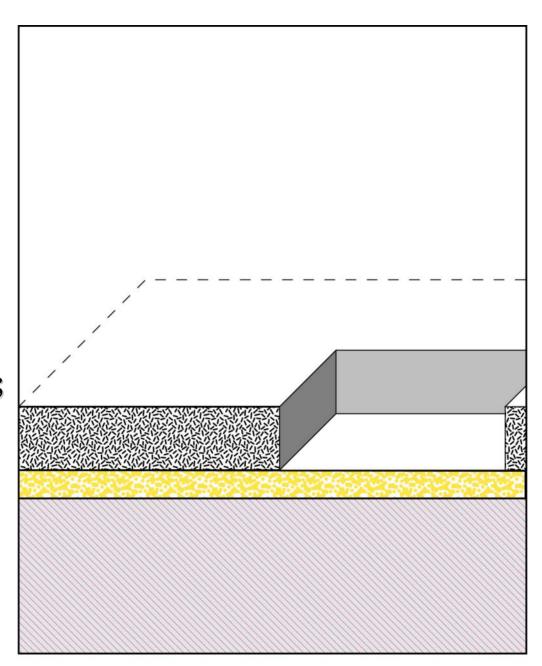
Oxidation;

Photoresist deposition;

Exposure;



- P- substrate;
- Oxidation;
- Photoresist deposition;
- Exposure;
- Development;
- Baking;



Oxidation;

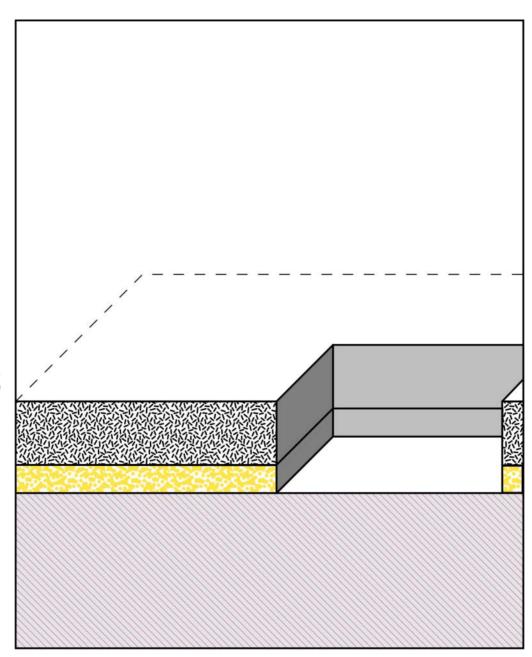
Photoresist deposition;

Exposure;

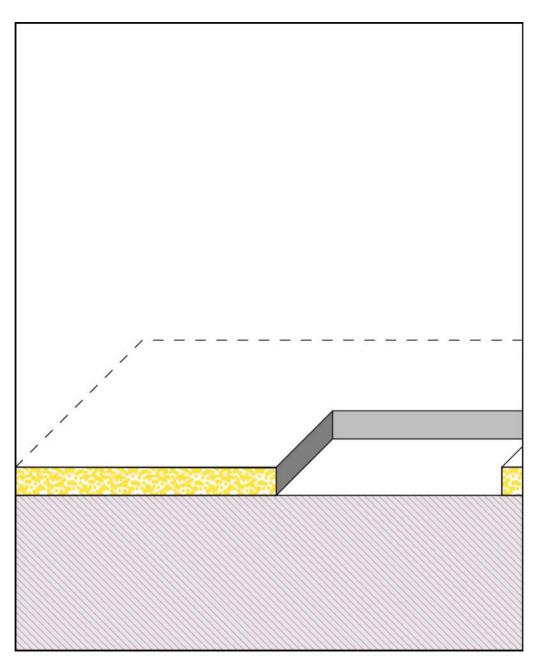
Development;

Baking;

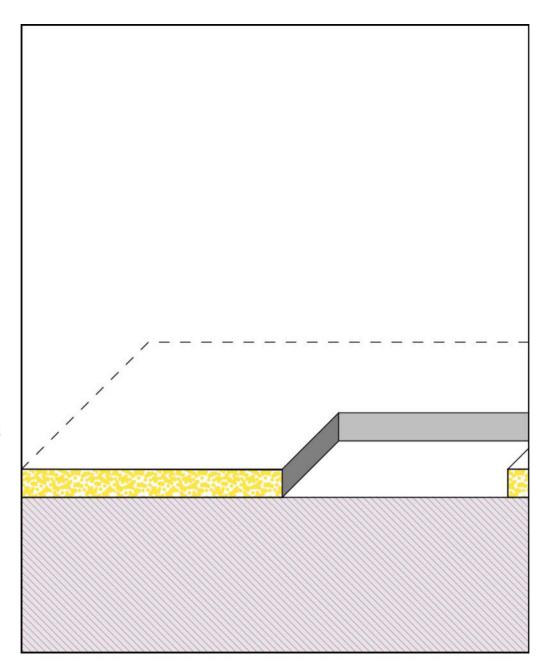
Etching;



- P- substrate;
- Oxidation;
- Photo-resist deposition;
- Exposure;
- Development;
- Baking;
- Etching;
- Photo-resist strip;
- Cleaning



- P- substrate;
- Oxidation;
- Well lithography:
 - Photo-resist deposition;
 - Exposure;
 - Development;
 - Baking;
 - Etching;
 - Photo-resist strip;
 - Cleaning.



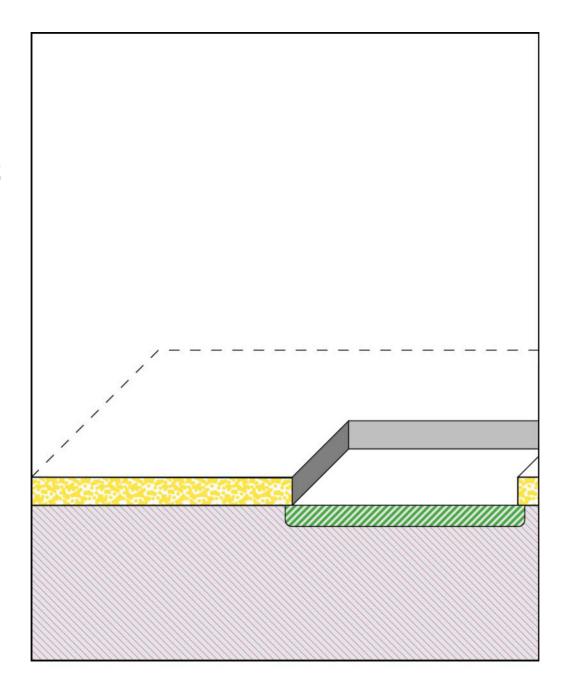
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Oxidation;

Well - lithography:

N-well prediffusion (Arsenic);

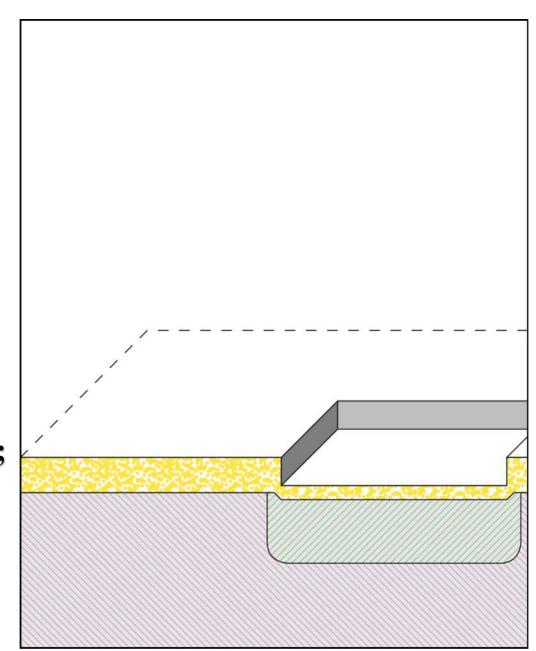


Oxidation;

Well - lithography:

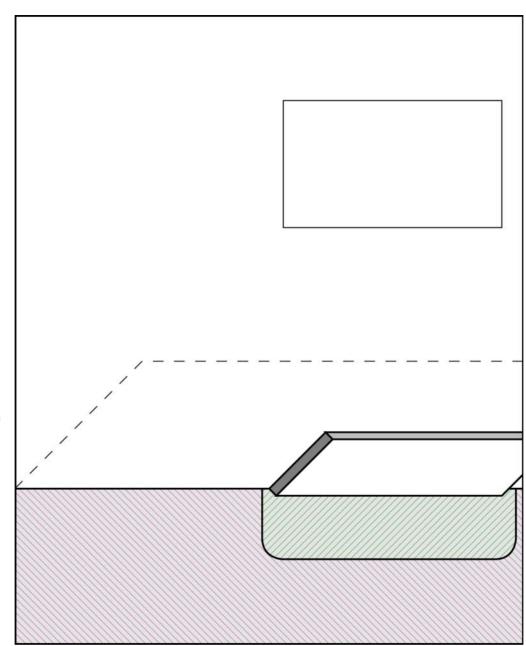
N-well prediffusion (Arsenic);

Well drive-in;



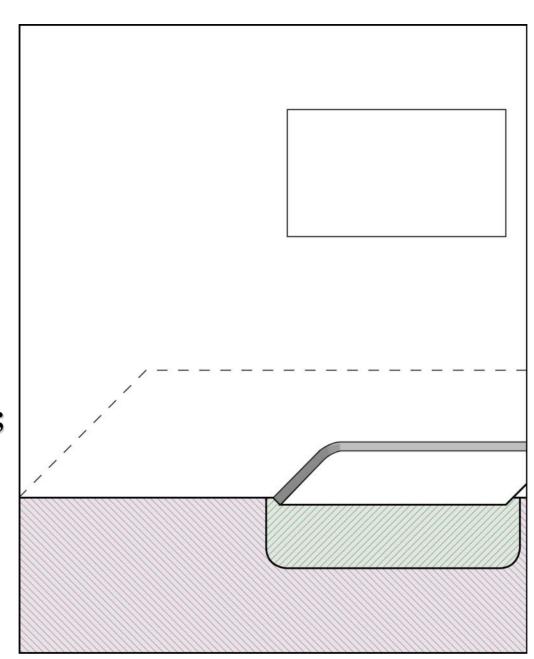
Oxidation;

- Well lithography:
- N-well prediffusion;
- Well drive-in;
- Oxide removal

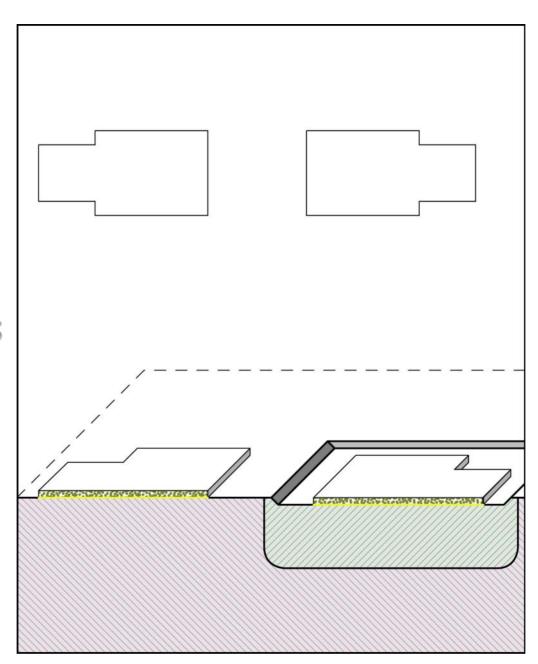


Oxidation;

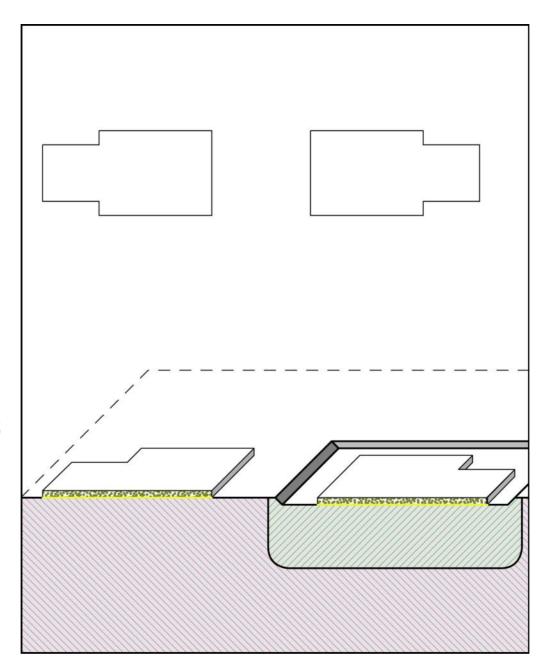
- Well lithography:
- N-well prediffusion;
- Well drive-in;
- Oxide rm.



- Well lithography:
- N-well prediffusion;
- Well drive-in;
- Oxide rm.
- Oxidation
- Nitride deposition;
- Active litho.



- Oxidation;
- Nitride deposition;
- Active litho.
 - Photo-resist deposition;
 - Exposure;
 - Development;
 - Baking;
 - Etching;
 - Photo-resist strip;
 - Cleaning



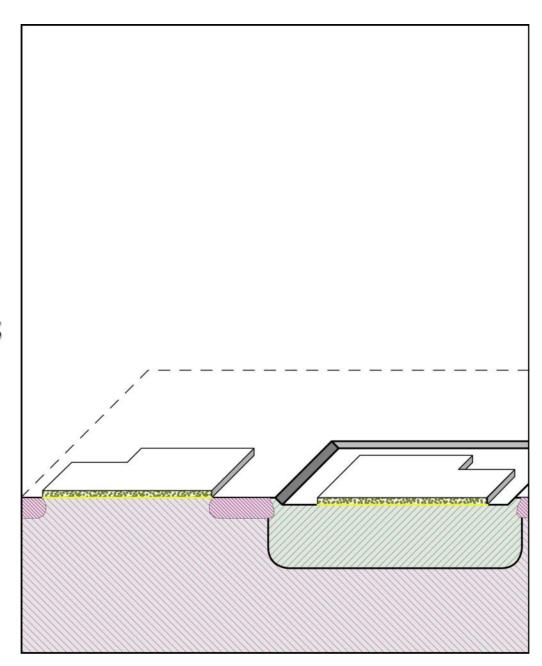
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Nitride deposition;

Active litho.

Channel-stop implantation;

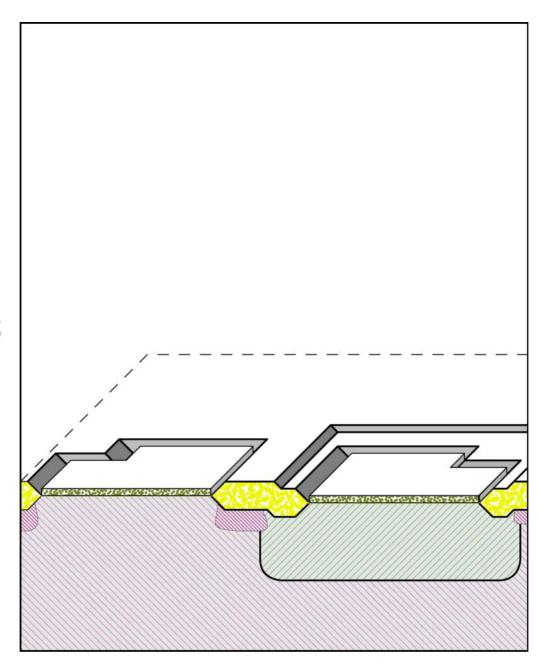


Nitride deposition;

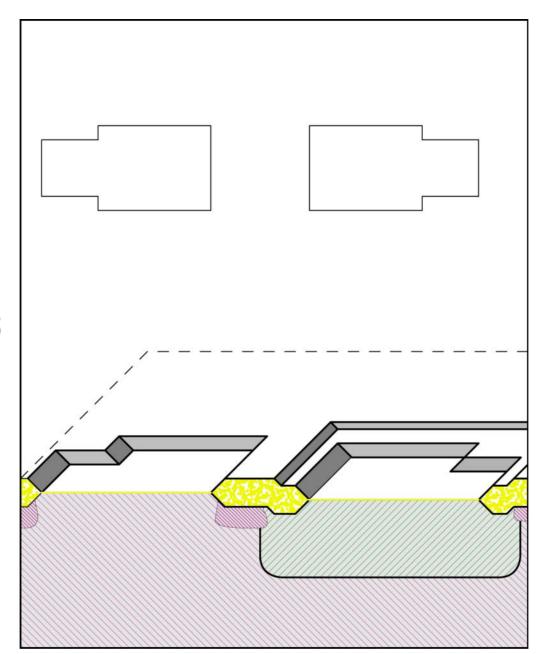
Active litho.

Channel-stop implantation;

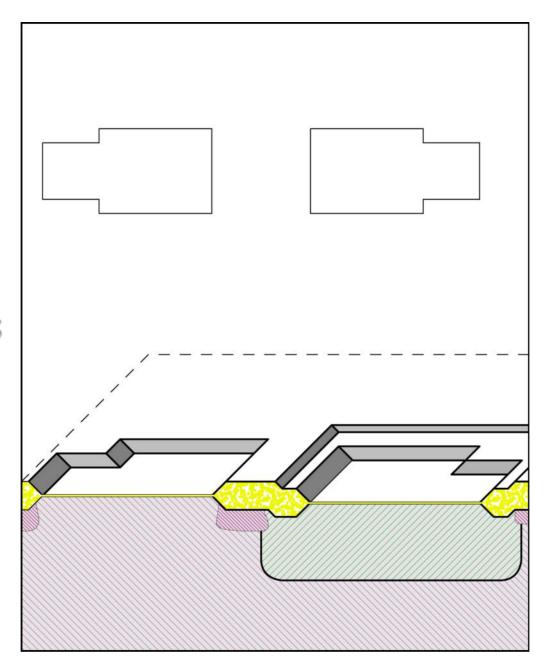
Field oxidation (FOX)



- Nitride deposition;
- Active litho.
- Channel-stop implantation;
- Field oxidation;
- Nitride rm.;
- Oxide rm.;
- Cleaning;

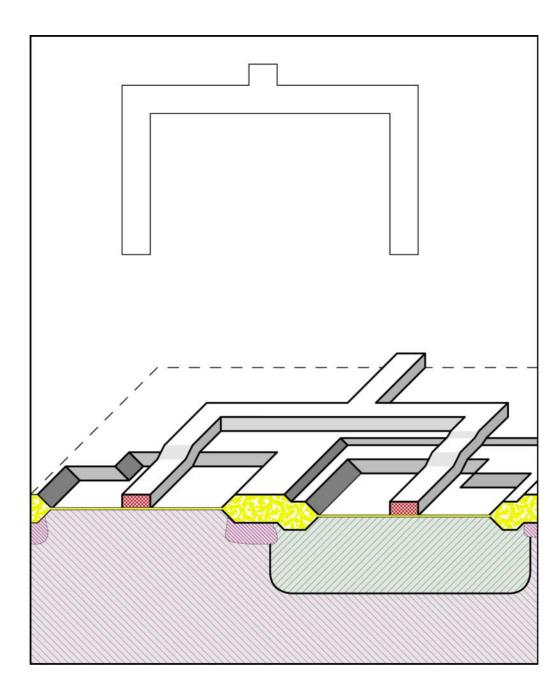


- Nitride deposition;
- Active litho.
- Channel-stop implantation;
- Field oxidation;
- Nitride rm.;
- Oxide rm.;
- Cleaning;
- Gate oxidation

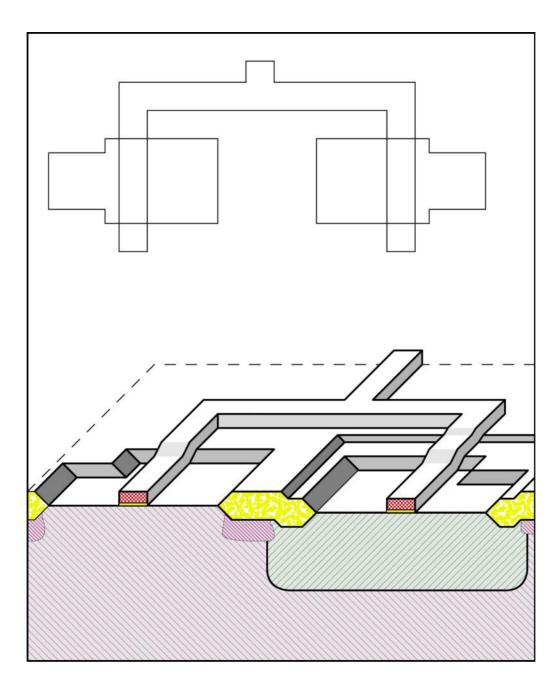


Gate oxidation (GOX);

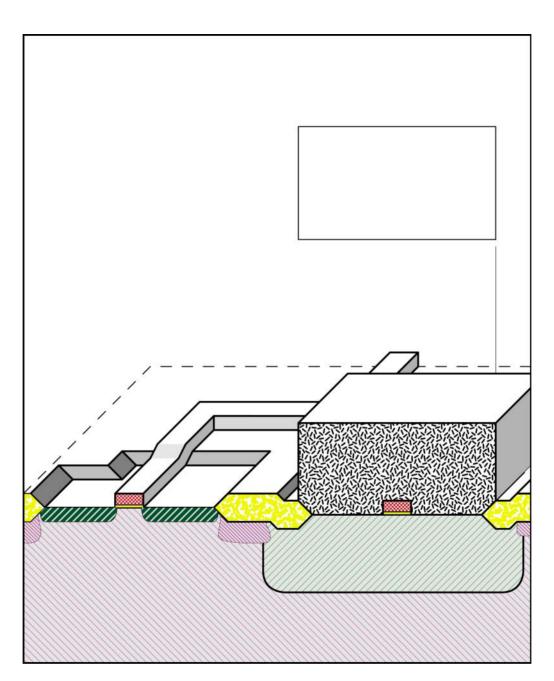
- Polysilicon (poly) deposition;
- Poly litho;



- Gate oxidation (GOX);
- Polysilicon(poly)deposition;
- Poly litho;
- GOX oxide rm.



- Gate oxidation (GOX);
- Polysilicon(poly)deposition;
- Poly litho;
- N litho;
 - Negative pr.
 - N (Phosphorus) implantation.



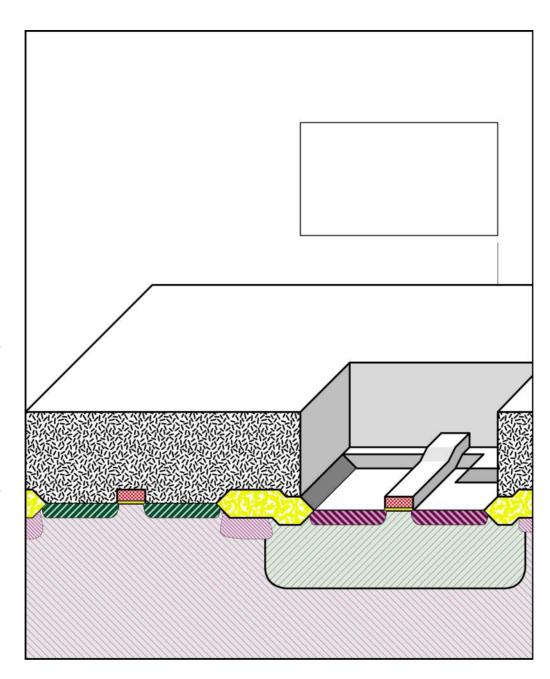
Poly litho;

N litho;

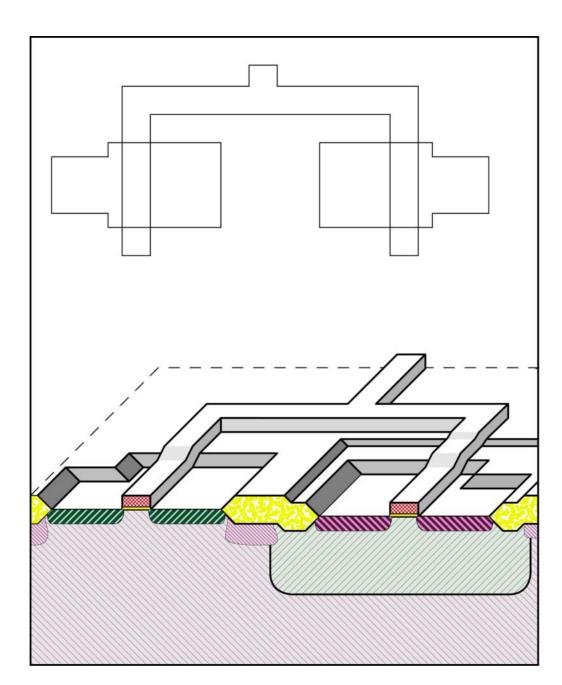
- Negative pr.
- N
 (Phosphorus)
 implantation.

P litho;

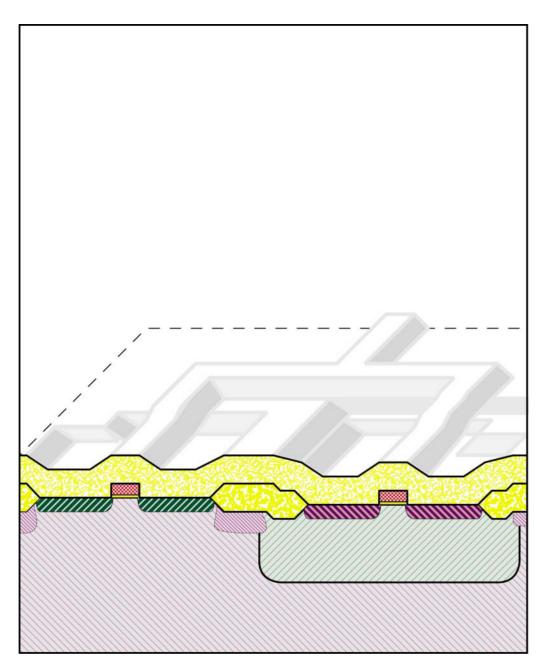
- Positive pr.
- P (Boron) implantation.



Transistors



- Poly litho;
- N litho;
 - Negative pr.
 - N (Phosphorus) implantation.
- ~ P litho;
 - Positive pr.
 - P (Boron) implantation.
- ChemicalVaporDeposited(CVD) oxide;

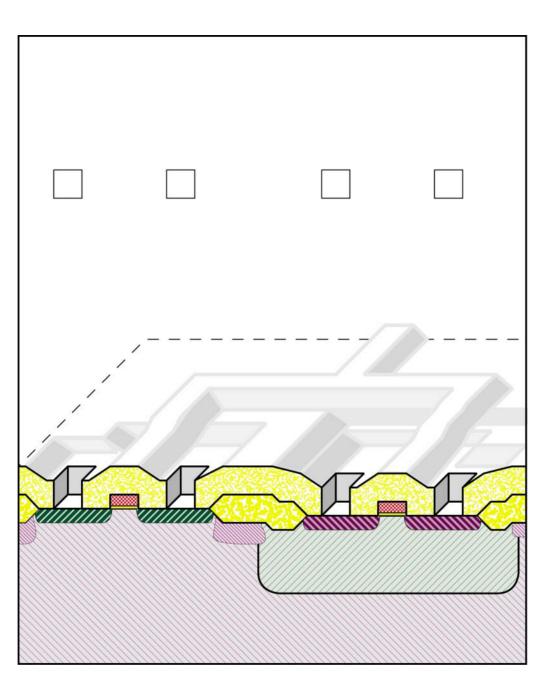


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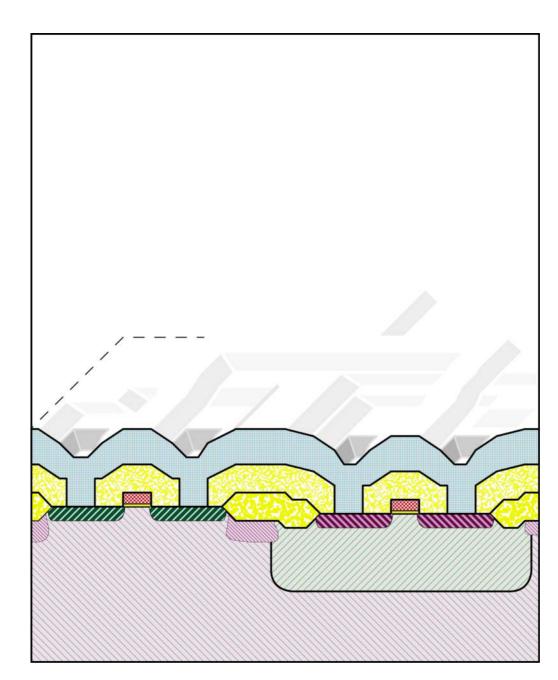
CVD oxide;

Contact
Litho;

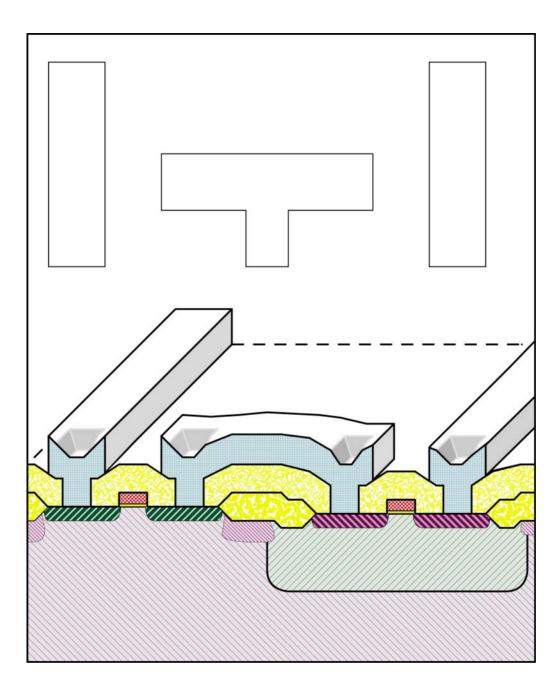


CVD oxide;

- Contact Litho;
- Metal-1 deposition;



- CVD oxide;
- ContactLitho;
- Metal-1 deposition;
- Metal-1
 Litho.



CVD oxide;

Contact Litho;

Metal-1 deposition;

Metal-1 Litho.

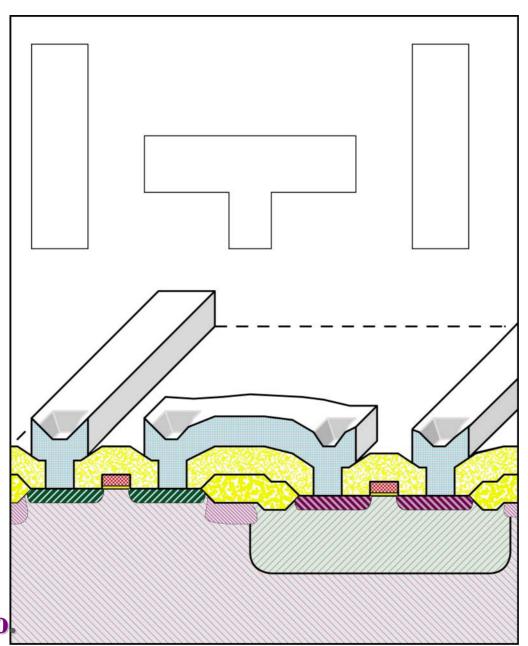
CVD oxide;

Via-1 Litho;

Metal-2 deposition;

Metal-2 Litho.

Over-glass deposition/litho.



Inverter

